Connector for microSD™ Card (Push-push Type)

SCHA Series

RoHS
compliant

Compact low-profile type most suitable for mobile phones.

Features

● Improved operability from a clear click feel.
● Good operational feel.

Applications

● For mobile phones, personal digital assistants, digital still cameras, compact audio equipment.

■Typical Specifications

Items		Specifications
Structure	Applicable media	microSD™ Card
	Mounting type	Surface mounting type
	Mounting style	Standard mount/Reverse mount
	Media ejection structure	Push-push type
Performance	Operating temperature range	−20℃ to ＋70℃
	Voltage proof	500V AC 1minute
	Insulation resistance （Initial）	1,000MΩ min.
	Contact resistance （Initial） — Connector contacts	100mΩ max.
	Contact resistance （Initial） — Detection switch	500mΩ max.
	Insertion and removal cycle	5,000cycles

■Product Line

Media ejection structure	Mounting system	Features	Stand-off （mm）	Packing system	Product No.	Drawing No.
Push-push type	Standard mount	Without switch	0	Taping	SCHA1A0101	1
		With switch			SCHA1B0100	2
	Reverse mount				SCHA2B0300	3

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■Dimensions
Standard mount

Unit:mm

No.	Style	PC board mounting hole dimensions (Viewed from the mounting face side)
1	**Without switch**	No parts area / Land area / No pattern area
2	**With switch**	Land area / No pattern area / No parts area

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17

■Dimensions
Reverse mount

Unit:mm
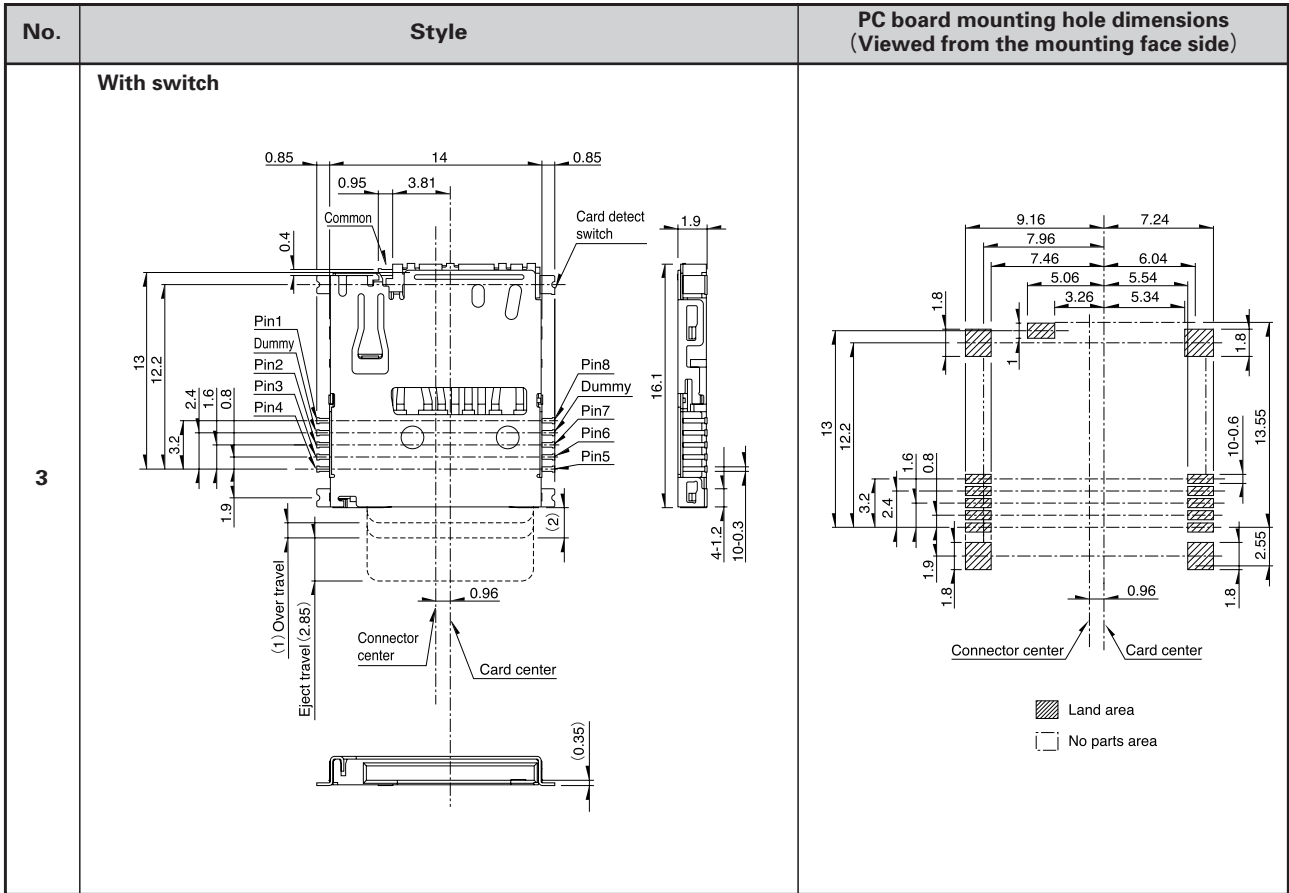
| No.	Style	PC board mounting hole dimensions (Viewed from the mounting face side)
3	**With switch**	

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Soldering Conditions

Example of Reflow Soldering Condition（Reference）

1. Heating method: Double heating method with infrared heater.
2. Temperature measurement: Thermocouple 0.1 to 0.2 ϕ CA（K）or CC（T）.
3. Temperature profile（Surface of products）.
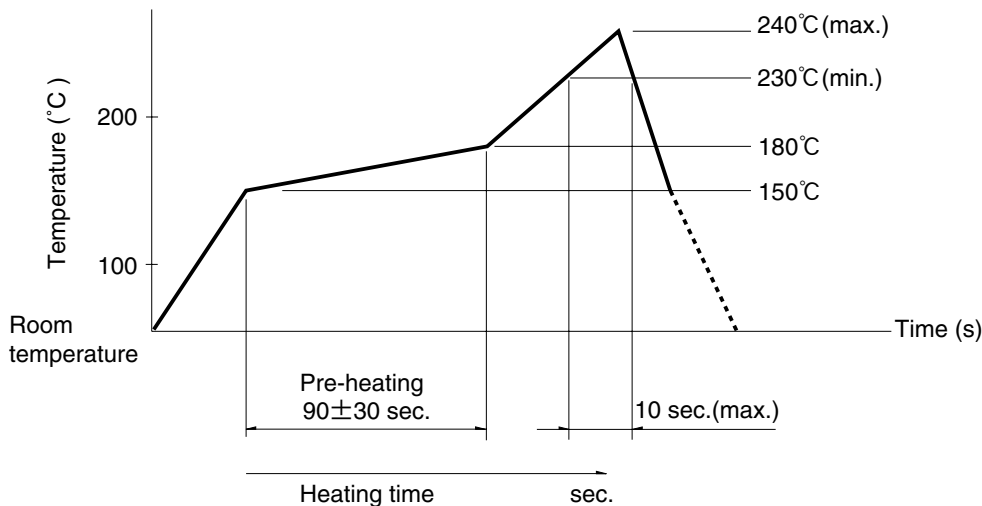
Cautions for using this product

1. When soldering terminals, there is a danger that load placed on the terminals may cause rattle, deformation or electrical degradation to occur depending on the conditions. Caution is therefore required.
2. Avoid use of water-soluble soldering flux, since it may corrode the product.
3. Check and conform to reflow soldering requirements under actual mass production conditions.
4. PC board warping may alter the characteristics. Please take this into consideration when designing patterns and layout.
5. The card specifications are provided by the above manufactures. Products by other manufactures may not be compliant with these specifications and are subject to change without prior notice.

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